Semiconductor device Package with Die Receiving Through-Hole and Connecting Through Hole and Method of the Same

ABSTRACT OF THE INVENTION

The present invention provides a semiconductor device package with the die receiving through hole and connecting through holes structure comprising a substrate with a die receiving through hole, connecting through holes structure and first contact pads on an upper surface and second contact pads on a lower surface of the substrate. A die is disposed within the die receiving through hole. A first adhesion material is formed under the die and a second adhesion material is filled in the gap between the die and sidewall of the die receiving though hole of the substrate. Further, a bonding wire is formed to couple and the bonding pads and the first contact pads. A dielectric layer is formed on the bonding wire, the die and the substrate.